

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An electrically conductive silicone rubber composition having improved adhesion, comprising

(A) 100 parts by weight of an organopolysiloxane having at least two aliphatic unsaturated groups in a molecule,

(B) 0.1 to 100 parts by weight of finely divided silica,

(C) 30 to 700 parts by weight of an electrically conductive powder having a construction comprising an inorganic filler or a resin particle covered with a nickel layer, which in turn is covered with a gold layer,

(D) 0.1 to 20 parts by weight of an adhesive aid, and

(E) a curing agent in an amount sufficient to cure the organopolysiloxane,

wherein component (D) is an organosilicon compound having in a molecule at least one SiH group and at least one group containing an aromatic ring and/or a carbonyl group, selected from the class consisting of epoxy, alkoxy and alkenyloxy groups, and wherein component (D) is a compound having at least one alkoxy group or epoxy group or both.

2. Cancelled.

3. (Previously Presented) The silicone rubber composition of claim 1, wherein component (C) is a metal-plated silica powder having a construction comprising silica covered with a nickel layer which in turn is covered with a gold layer.

4. - 6. Cancelled

7. (Previously Presented) The silicone rubber composition of claim 1, wherein the curing agent (E) is an organic peroxide.

8. (Previously Presented) The silicone rubber composition of claim 1, wherein the curing agent (E) is an addition reaction-type curing agent comprising an organohydrogen-polysiloxane having at least two SiH groups in a molecule and a platinum group metal catalyst.

9. (Previously Presented) An article comprising a substrate of a metal or resin and a coating of the conductive silicone rubber composition of claim 1 applied and cured to the substrate without a primer, the cured coating of the composition being integrated with the substrate.

10. (Previously Presented) The silicone rubber composition of claim 1, wherein the metal-plated powder has a silicon-based polymeric compound with a reducing property between the inorganic filler or resin and the nickel.

11. (Previously Presented) The silicone rubber composition of claim 3, wherein the metal-plated silica powder has a silicon-based polymeric compound with a reducing property between the silica and the nickel.

12. (Previously Presented) The silicone rubber composition of claim 11, wherein the silicon-based polymeric compound with a reducing property is one selected from the group consisting of polysilanes, polycarbosilanes, polysiloxanes and polysilazanes having silicon-silicon or silicon-hydrogen bonds.

13. (Previously Presented) The silicone rubber composition of claim 3, wherein the metal-plated silica powder has a ceramic between the silica and the nickel formed by heat treating a silicon-based compound with a reducing property between the silica and the nickel in the presence of an inert gas at a temperature of at least 200°C to convert the silicon-based polymeric compound to the ceramic.

14. (Previously Presented) The silicone rubber composition of claim 1, wherein component (C) is a powder having an average particle size within a range of 0.05 to 100 μm .

15. (Previously Presented) The silicone rubber composition of claim 1, wherein component (C) is a powder having an average particle size within a range of 0.1 to 10 μm .

16. (Previously Presented) The silicone rubber composition of claim 1, wherein component (C) is a powder having a specific surface area of at most 1 m^2/g .

17. (Previously Presented) The silicone rubber composition of claim 1, wherein component (C) is present in an amount of 50 to 600 parts by weight.